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| **产品名称** | **密级** |
| *B818-260* | 内部公开 |
| **产品版本** | Total 6 pages |
| *B818-260-BD 8.0.1.99(H100SP4C00)* |

*B818-260-BD 8.0.1.99(H100SP4C00)*

烧片软件版本说明书

|  |  |  |  |
| --- | --- | --- | --- |
| Prepared by | 张瑞辰 | Date | 2019-01-10 |
| Reviewed by |  |  |  |
| Approved by |  |  |  |



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修订记录

|  |  |  |  |
| --- | --- | --- | --- |
| 时间 | 修订版本 | 修订内容 | 作者 |
| 2018-10-27 | *1.0* | V3第一轮预试制 | 张瑞辰z00423811 |
| 2018-10-31 | *1.1* | V3第二轮预试制 | 张瑞辰z00423811 |
| 2018-10-31 | *1.2* | VDF客户样机试制 | 张瑞辰z00423811 |
| 2018-12-17 | *1.3* | VN1第一轮预试制 | 张瑞辰z00423811 |
| 2019-01-10 | *1.4* | VN2第一轮预试制 | 张瑞辰z00423811 |
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[*4* 其他 6](#_Toc505948958)

# 缩略语

|  |  |
| --- | --- |
| 缩略语 | 描述说明 |
|  |  |
|  |  |

# 硬件信息

## **版本描述**

|  |  |
| --- | --- |
| **Hardware Version:** | WL1B818M Ver.C |
| **Platform & Chipset:** | Balong V7R65 |

## **较前一版本的变更**

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  |  |
| 2 |  |  |
| 3 |  |  |
| 4 |  |  |
| 5 |  |  |
| 6 |  |  |

## **遗留问题**

| Index | Case ID | Issue Description |
| --- | --- | --- |
| NA |  |  |
|  |  |  |

# 烧片软件

## **版本描述**

|  |  |
| --- | --- |
| **Firmware Version ：** | *BD 8.0.1.99(H100SP4C00)* |
| **Baseline information：** | Balong V7R65 C31B100 |
| **ProductLine WinDriver：** | The newest version |

## **历次版本变更**

### *BD 8.0.1.99(H70SP5C00)*

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  | 首版本 |
| 2 |  |  |

### *BD 8.0.1.99(H70SP6C00)*

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  | 修改射频NV增加CA特殊场景下的2R path |
| 2 |  |  |

### *BD 8.0.1.99(H70SP7C00)*

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  | 主频：解决V3产线试制功率CPK问题，修改包含CT RSSI，EDGE功率，B1\_1路功率及antpower |
| 2 |  | WIFI：V3 烧片功率规格刷新 |

### *BD 8.0.1.99(H100SP2C00)*

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  | 主频：antpower优化调试；W TX校准功率调试；RSE问题合入；时序优化；EDGE功率优化；CA相关问题解决 |
| 2 |  | WIFI：参数优化提取 |
| 3 |  | 软件基线切换至海思商用分支基线B100 |

### *BD 8.0.1.99(H100SP4C00)*

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  | GSM校准及B42C额外杂散问题射频参数优化上库。 |

## 遗留问题

| Index | Case ID | Issue Description |
| --- | --- | --- |
| 1 |  |  |
| 2 |  |  |
| 3 |  |  |
| 4 |  |  |
| 5 |  |  |

# 其他